Product Change Notification - JAON-30IVHP500

Date: 17 Nov 2017

Product Category: 8-bit PIC Microcontrollers Capacitive Touch Sensors 16-Bit - Microcontrollers and Digital Signal Controllers

Notification subject: CCB 3001 Final Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

Notification text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN Affected CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

Pre Change:
Assembled at MTAI using palladium coated copper (PdCu) bond wire.

Post Change:
Assembled at MTAI using palladium coated copper (PdCu) bond wire or assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand Branch (MMT)
Wire material	PdCu Wire	PdCu Wire	CuPdAu Wire
Die attach material	3280	3280	3280
Molding compound material	G600	G600	G600
Lead frame material	CDA194	CDA194	CDA194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:
In Progress

Estimated First Ship Date:
December 17, 2017 (date code: 1751)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2017				-->	November 2017				December 2017				
Workweek	27	28	29	30		44	45	46	47	48	49	50	51	52
Initial PCN Issue Date	X													
Qual Report Availability								X						
Final PCN Issue Date								X						
Estimated Implementation Date													X	

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN Qual Report.

Revision History:
July 6, 2017: Issued initial notification.
November 17, 2017: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on December 17, 2017

The change described in this PCN does not alter Microchip s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN JAON-30IVHP500 Affected CPN.pdf
PCN JAON-30IVHP500 Qual Report.pdf
PCN JAON-30IVHP500 Affected CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip s products or services."

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: JAON-30IVHP500

Date

October 31, 2017

Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package.
CN	ES114909
QUAL ID	Q17138
MP CODE	LEBC14N2XAXF
Part No.	PIC18F25K80-E/SS
Bonding No.	BDM-001364 Rev. A
CCB No.	3001
<u>Package</u>	
Type	28L SSOP
Package size	209 mils
Die thickness	15 mils
Die size	135.50 x 138.30 mils
<u>Lead Frame</u>	
Paddle size	153 x 200 mils
Material	CDA194
Surface	Bare Cu
Process	Stamped
Lead Lock	No
Part Number	10102834
Treatment	Roughened
<u>Material</u>	
Epoxy	3280
Wire	CuPdAu wire
Mold Compound	G600
Plating Composition	Matte Tin

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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-181901187.000	GRSM417480228.120	1731V4Q
MMT-182000212.000	GRSM417480228.100	1732V4R
MMT-182000436.000	GRSM417480228.120	1732WE4

Result [X] Pass [ ] Fail [ ] ____________________

28L SSOP (.209") assembled by MMT (NSEB) pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDEC J-STD-020D	135	0/135	Pass	
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test :**+25°C and 125°C System: J750 Bake 150°C, 24 hrs System: CHINEE 85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 **Electrical Test :**+25°C and 125°C System: J750	JESD22-A113	693(0)	693 693 693 693 0/693	Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** (Standard) -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +125°C System: J750		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (> 2.5 grams)		15 (0)	0/15	Pass	
	Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** (Standard) +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: J750		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** (Standard) +130°C/85%RH, 96 hrs. **Bias Volt:** 5.5 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test:+ 25°C and 125°C System: J750		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs System: SHEL LAB	JESD22-A103		45		45 units
	Electrical Test :+25°C and 125°C System: J750		45(0)	0/45	Pass	
Physical Dimensions	Physical Dimension, 30 units from 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22-B116	30 (0) bonds	0/30	Pass	

JAON-30IVHP500 - CCB 3001 Final Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

Affected Catalog Part Numbers (CPN)

PCN_JAON-30IVHP500
CATALOG_PART_NBR
C0001RIC00-I/SS
C0001RIC00T-I/SS
C0003RIC03T-I/SS028
C0026RIC01-I/SS029
C0026RIC01T-I/SS029
HA0130-I/SS
HA0130T-I/SS
HA1018-I/SS
HA1127-I/SS
HA1127T-I/SS
HA1138-I/SS
HA1138T-I/SS
HA1631-I/SO
HA1631T-I/SO
HA1839-I/SS
HA1839T-I/SS
HA1930C-I/SS
HA2003-I/SS
MCV282B-I/SS
MCV283B-I/SS
MCV283BT-I/SS
MTCH6102-I/SS
MTCH6102T-I/SS
MTR5010-I/SS
MTR5010T-I/SS
MTR9833-I/SS
MTR9833T-I/SS
PIC16F1512-E/SS
PIC16F1512-I/SS
PIC16F1512-I/SSC03
PIC16F1512-I/SSC04
PIC16F1512T-I/SS
PIC16F1512T-I/SSC03
PIC16F1512T-I/SSC04
PIC16F1513-E/SS
PIC16F1513-I/SS
PIC16F1513T-E/SS
PIC16F1513T-I/SS
PIC16F1516-E/SS
PIC16F1516-I/SS
PIC16F1516-I/SS024
PIC16F1516-I/SSC01
PIC16F1516-I/SSC02

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC16F1516T-E/SS
PIC16F1516T-I/SS
PIC16F1516T-I/SS021
PIC16F1516T-I/SS022
PIC16F1516T-I/SS024
PIC16F1516T-I/SS025
PIC16F1516T-I/SSC01
PIC16F1516T-I/SSC02
PIC16F1518-E/SS
PIC16F1518-I/SS
PIC16F1518T-I/SS
PIC16F1713-E/SS
PIC16F1713-I/SS
PIC16F1713T-I/SS
PIC16F1716-E/SS
PIC16F1716-I/SS
PIC16F1716T-I/SS
PIC16F1718-E/SS
PIC16F1718-I/SS
PIC16F1718T-I/SS
PIC16F1773-E/SS
PIC16F1773-I/SS
PIC16F1773T-I/SS
PIC16F1776-E/SS
PIC16F1776-I/SS
PIC16F1776T-I/SS
PIC16F1778-E/SS
PIC16F1778-I/SS
PIC16F1778T-I/SS
PIC16F1782-E/SS
PIC16F1782-I/SS
PIC16F1782T-E/SS
PIC16F1782T-I/SS
PIC16F1783-E/SS
PIC16F1783-I/SS
PIC16F1783T-I/SS
PIC16F1786-E/SS
PIC16F1786-I/SS
PIC16F1786T-I/SS
PIC16F1788-E/SS
PIC16F1788-I/SS
PIC16F1788-I/SSC01
PIC16F1788T-E/SS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC16F1788T-I/SS
PIC16F1788T-I/SS023
PIC16F1788T-I/SSC01
PIC16F1933-E/SS
PIC16F1933-I/SS
PIC16F1933-I/SSC01
PIC16F1933T-E/SS
PIC16F1933T-I/SS
PIC16F1936-E/SS
PIC16F1936-I/SS
PIC16F1936-I/SS029
PIC16F1936-I/SSC01
PIC16F1936-I/SSC03
PIC16F1936T-E/SS
PIC16F1936T-I/SS
PIC16F1936T-I/SSC03
PIC16F1938-E/SS
PIC16F1938-I/SS
PIC16F1938-I/SSC03
PIC16F1938T-E/SS
PIC16F1938T-I/SS
PIC16F1938T-I/SSC03
PIC16F722A-E/SS
PIC16F722A-I/SS
PIC16F722A-I/SS023
PIC16F722AT-E/SS
PIC16F722AT-I/SS
PIC16F722AT-I/SS020
PIC16F722AT-I/SS021
PIC16F722AT-I/SS022
PIC16F722AT-I/SS024
PIC16F722-E/SS
PIC16F722-I/SS
PIC16F722T-E/SS
PIC16F722T-I/SS
PIC16F723A-E/SS
PIC16F723A-I/SS
PIC16F723AT-E/SS
PIC16F723AT-I/SS
PIC16F723-E/SS
PIC16F723-I/SS
PIC16F723T-E/SS
PIC16F723T-I/SS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC16F726-E/SS
PIC16F726-I/SS
PIC16F726-I/SS035
PIC16F726-I/SS040
PIC16F726-I/SSC06
PIC16F726T-E/SS
PIC16F726T-I/SS
PIC16F726T-I/SS021
PIC16F726T-I/SS022
PIC16F726T-I/SS024
PIC16F726T-I/SS025
PIC16F726T-I/SS026
PIC16F726T-I/SS027
PIC16F726T-I/SS028
PIC16F726T-I/SS029
PIC16F726T-I/SS030
PIC16F726T-I/SS031
PIC16F726T-I/SS032
PIC16F726T-I/SS034
PIC16F726T-I/SS036
PIC16F726T-I/SS037
PIC16F726T-I/SS038
PIC16F726T-I/SS039
PIC16F726T-I/SSC06
PIC16LF1512-E/SS
PIC16LF1512-I/SS
PIC16LF1512T-I/SS
PIC16LF1513-E/SS
PIC16LF1513-I/SS
PIC16LF1513T-I/SS
PIC16LF1516-E/SS
PIC16LF1516-I/SS
PIC16LF1516-I/SSC04
PIC16LF1516T-I/SS
PIC16LF1516T-I/SSC04
PIC16LF1518-E/SS
PIC16LF1518-I/SS
PIC16LF1518T-I/SS
PIC16LF1566-E/SS
PIC16LF1566-I/SS
PIC16LF1566T-I/SS
PIC16LF1713-E/SS
PIC16LF1713-I/SS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC16LF1713T-I/SS
PIC16LF1716-E/SS
PIC16LF1716-I/SS
PIC16LF1716T-I/SS
PIC16LF1718-E/SS
PIC16LF1718-I/SS
PIC16LF1718T-I/SS
PIC16LF1773-E/SS
PIC16LF1773-I/SS
PIC16LF1773T-I/SS
PIC16LF1776-E/SS
PIC16LF1776-I/SS
PIC16LF1776T-I/SS
PIC16LF1778-E/SS
PIC16LF1778-I/SS
PIC16LF1778T-I/SS
PIC16LF1782-E/SS
PIC16LF1782-I/SS
PIC16LF1782T-I/SS
PIC16LF1783-E/SS
PIC16LF1783-I/SS
PIC16LF1783-I/SSC01
PIC16LF1783-I/SSC02
PIC16LF1783T-I/SS
PIC16LF1783T-I/SSC01
PIC16LF1783T-I/SSC02
PIC16LF1786-E/SS
PIC16LF1786-I/SS
PIC16LF1786T-I/SS
PIC16LF1788-E/SS
PIC16LF1788-I/SS
PIC16LF1788T-I/SS
PIC16LF1902-E/SS
PIC16LF1902-I/SS
PIC16LF1902T-I/SS
PIC16LF1903-E/SS
PIC16LF1903-I/SS
PIC16LF1903T-I/SS
PIC16LF1906-E/SS
PIC16LF1906-I/SS
PIC16LF1906T-I/SS
PIC16LF1933-E/SS
PIC16LF1933-I/SS

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PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC16LF1933T-E/SS
PIC16LF1933T-I/SS
PIC16LF1936-E/SS
PIC16LF1936-I/SS
PIC16LF1936T-I/SS
PIC16LF1938-E/SS
PIC16LF1938-I/SS
PIC16LF1938T-I/SS
PIC16LF1938T-I/SS020
PIC16LF1938T-I/SS022
PIC16LF1938T-I/SS024
PIC16LF722A-E/SS
PIC16LF722A-I/SS
PIC16LF722AT-I/SS
PIC16LF722-E/SS
PIC16LF722-I/SS
PIC16LF722T-I/SS
PIC16LF723A-E/SS
PIC16LF723A-I/SS
PIC16LF723A-I/SS021
PIC16LF723A-I/SSC01
PIC16LF723A-I/SSC02
PIC16LF723AT-I/SS
PIC16LF723AT-I/SS020
PIC16LF723AT-I/SS021
PIC16LF723AT-I/SS023
PIC16LF723AT-I/SS024
PIC16LF723AT-I/SS025
PIC16LF723AT-I/SS026
PIC16LF723AT-I/SS027
PIC16LF723AT-I/SSC02
PIC16LF723-E/SS
PIC16LF723-I/SS
PIC16LF723T-I/SS
PIC16LF726-E/SS
PIC16LF726-I/SS
PIC16LF726-I/SSC02
PIC16LF726T-I/SS
PIC16LF726T-I/SS020
PIC16LF726T-I/SS021
PIC16LF726T-I/SS022
PIC16LF726T-I/SS023
PIC18F23K20-E/SS

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PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC18F23K20-I/SS
PIC18F23K20T-E/SS
PIC18F23K20T-I/SS
PIC18F23K22-E/SS
PIC18F23K22-I/SS
PIC18F23K22T-E/SS
PIC18F23K22T-I/SS
PIC18F24K20-E/SS
PIC18F24K20-I/SS
PIC18F24K20-I/SSC03
PIC18F24K20T-E/SS
PIC18F24K20T-I/SS
PIC18F24K20T-I/SS031
PIC18F24K20T-I/SSC01
PIC18F24K20T-I/SSC03
PIC18F24K20T-I/SSC04
PIC18F24K20T-I/SSHP2
PIC18F24K22-E/SS
PIC18F24K22-I/SS
PIC18F24K22T-I/SS
PIC18F24K50-E/SS
PIC18F24K50-I/SS
PIC18F24K50T-I/SS
PIC18F25K20-E/SS
PIC18F25K20-E/SSC13
PIC18F25K20-E/SSC14
PIC18F25K20-I/SS
PIC18F25K20-I/SSC01
PIC18F25K20-I/SSC09
PIC18F25K20-I/SSC15
PIC18F25K20-I/SSLPR
PIC18F25K20T-E/SS
PIC18F25K20T-E/SSC13
PIC18F25K20T-I/SS
PIC18F25K20T-I/SS028
PIC18F25K20T-I/SSC01
PIC18F25K20T-I/SSC09
PIC18F25K20T-I/SSC15
PIC18F25K20T-I/SSC17
PIC18F25K22-E/SS
PIC18F25K22-I/SS
PIC18F25K22T-E/SS
PIC18F25K22T-I/SS

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PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC18F25K50-E/SS
PIC18F25K50-I/SS
PIC18F25K50T-I/SS
PIC18F25K80-E/SS
PIC18F25K80-H/SS
PIC18F25K80-I/SS
PIC18F25K80T-E/SS
PIC18F25K80T-I/SS
PIC18F26K20-E/SS
PIC18F26K20-E/SSC04
PIC18F26K20-E/SSC05
PIC18F26K20-I/SS
PIC18F26K20-I/SSLPR
PIC18F26K20T-E/SS
PIC18F26K20T-E/SSC04
PIC18F26K20T-E/SSC05
PIC18F26K20T-I/SS
PIC18F26K20T-I/SS027
PIC18F26K20T-I/SS031
PIC18F26K20T-I/SS038
PIC18F26K20T-I/SS039
PIC18F26K20T-I/SS041
PIC18F26K20T-I/SS044
PIC18F26K20T-I/SSLPR
PIC18F26K22-E/SS
PIC18F26K22-I/SS
PIC18F26K22T-E/SS
PIC18F26K22T-I/SS
PIC18F26K80-E/SS
PIC18F26K80-H/SS
PIC18F26K80-I/SS
PIC18F26K80T-E/SS
PIC18F26K80T-H/SS
PIC18F26K80T-I/SS
PIC18LF23K22-E/SS
PIC18LF23K22-I/SS
PIC18LF23K22T-I/SS
PIC18LF24K22-E/SS
PIC18LF24K22-I/SS
PIC18LF24K22T-I/SS
PIC18LF24K50-E/SS
PIC18LF24K50-I/SS
PIC18LF24K50T-I/SS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC18LF25K22-E/SS
PIC18LF25K22-I/SS
PIC18LF25K22-I/SSC02
PIC18LF25K22T-E/SS
PIC18LF25K22T-I/SS
PIC18LF25K50-E/SS
PIC18LF25K50-I/SS
PIC18LF25K50T-I/SS
PIC18LF25K80-I/SS
PIC18LF25K80T-I/SS
PIC18LF26K22-E/SS
PIC18LF26K22-I/SS
PIC18LF26K22-I/SSC03
PIC18LF26K22T-E/SS
PIC18LF26K22T-I/SS
PIC18LF26K22T-I/SS021
PIC18LF26K22T-I/SS022
PIC18LF26K22T-I/SSC03
PIC18LF26K80-I/SS
PIC18LF26K80T-I/SS
PIC24F08KA102-E/SS
PIC24F08KA102-I/SS
PIC24F08KA102T-E/SS
PIC24F08KL302-E/SS
PIC24F08KL302-I/SS
PIC24F08KL302T-I/SS
PIC24F08KL402-E/SS
PIC24F08KL402-I/SS
PIC24F08KL402T-I/SS
PIC24F08KM202-I/SS
PIC24F16KA102-E/SS
PIC24F16KA102-I/SS
PIC24F16KA102T-I/SS
PIC24F16KA302-E/SS
PIC24F16KA302-I/SS
PIC24F16KA302T-I/SS
PIC24F16KL402-E/SS
PIC24F16KL402-I/SS
PIC24F16KL402T-I/SS
PIC24F16KM102-I/SS
PIC24F16KM202-I/SS
PIC24F32KA302-E/SS
PIC24F32KA302-I/SS

JAON-30IVHP500 - CCB 3001 Final Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

Affected Catalog Part Numbers (CPN)

PCN_JAON-30IVHP500
CATALOG_PART_NBR
PIC24F32KA302T-I/SS
PIC24FV08KM202-I/SS
PIC24FV16KA302-E/SS
PIC24FV16KA302-I/SS
PIC24FV16KA302T-E/SS
PIC24FV16KA302T-I/SS
PIC24FV16KM102-I/SS
PIC24FV16KM202-E/SS
PIC24FV16KM202-I/SS
PIC24FV16KM202T-E/SS
PIC24FV16KM202T-I/SS
PIC24FV32KA302-E/SS
PIC24FV32KA302-I/SS
PIC24FV32KA302T-E/SS
PIC24FV32KA302T-I/SS